

The Device Technologies, Inc.'s products listed below related to implementation of the European Union Restriction of Hazardous Substances (RoHS) Directive (2002/95/EC) and the Waste Electrical and Electronic Equipment (WEEE) Directive. Compliance date: January 1, 2000.

The information in this correspondence pertains to the following Device Technologies, Inc. products:

- Spring-Fast® Wire Protection Grommet Edging**
- Push-Lok® Printed Circuit Board Stand-off**
- Fast-Drop® Fiber Minimum Bend Radius Control Module**
- Push-Mount™ Cable Tie**
- Seal-Fast™ Enclosure Edge Seal**
- Trim-Fast™ Edge Trim**
- Protect-Fast™ Braided Sleeving**

On behalf of Device Technologies, Inc., to the best of DTi's knowledge, the following chemicals are not present at or above the concentrations indicated, in the products listed above:

SUBSTANCE	PRODUCT CONTAINS	PRODUCT DOES NOT CONTAIN
Lead (if alloying element in steel, aluminum or copper, provide percent lead content by weight)		X
Mercury		X
Cadmium		X
Hexavalent Chromium		X
Polybrominated Biphenyls (PBB)		X
Polybrominated Diphenyl Ethers (PBDE)		X

In preparing this response, Device Technologies, Inc. Engineering department has relied in part on information provided by DTi suppliers.

All packaging and electrical components for the above noted products comply with the European Union requirements. All packaging will be so identified with the lead free label:



For additional information please contact us by email: [customerservice@devicetech.com](mailto:customerservice@devicetech.com) phone: (508) 229-2000 or mail: Device Technologies, Inc., 155 Northboro Rd., Unit 8, Southborough, MA 01772.